

DESCRIPTION

SMC2869ESC used trench technology are well suited for high efficiency fast switching applications, this MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, this devices are well suited for applications in the small surface mount package.

PART NUMBER INFORMATION

SMC 2869 E SC - TR G
 a b c d e f

- a : Company name
- b : Product Serial number
- c : ESD Protection
- d : Package code SC: SOT-523
- e : Handling code TR: Tape&Reel
- f : Green produce code G: RoHS Compliant

FEATURES

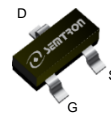
$V_{DS}=-20V$, $I_D=-0.54A$

- $R_{DS(ON)}=560m\Omega(Typ.)@V_{GS}=-4.5V$
- $R_{DS(ON)}=740m\Omega(Typ.)@V_{GS}=-2.5V$
- $R_{DS(ON)}=1000m\Omega(Typ.)@V_{GS}=-1.8V$
- $R_{DS(ON)}=1400m\Omega(Typ.)@V_{GS}=-1.5V$

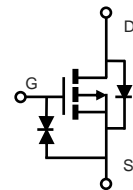
- ◆ High-speed switching, Low On-resistance
- ◆ 1.5V Low gate drive
- ◆ ESD protected

APPLICATIONS

- ◆ Load switch application for portable



SOT-523



ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units	
V_{DSS}	Drain-Source Voltage	-20	V	
V_{GSS}	Gate-Source Voltage	± 8	V	
I_D	Continuous Drain Current ^A	$T_A=25^{\circ}C$	-0.54	A
		$T_A=70^{\circ}C$	-0.43	A
I_{DM}	Pulsed Drain Current ^B	-1.8	A	
P_D	Power Dissipation ^A	$T_A=25^{\circ}C$	0.3	W
		$T_A=70^{\circ}C$	0.19	W
T_J	Operation Junction Temperature	-55/150	$^{\circ}C$	
T_{STG}	Storage Temperature Range	-55/150	$^{\circ}C$	

THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^{AC}		415	$^{\circ}C/W$
	Steady-State			

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ Unless otherwise noted)

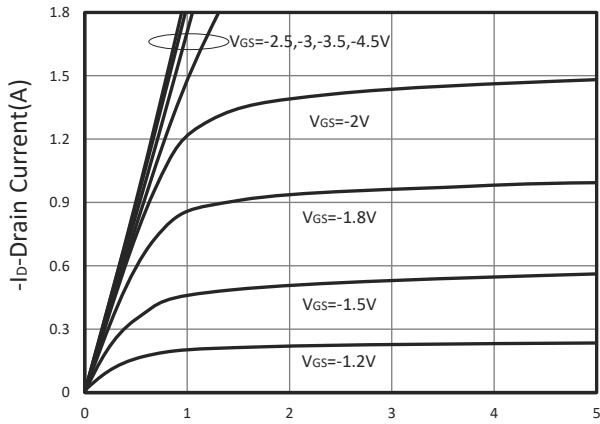
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250 μ A	-20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250 μ A	-0.5	-0.7	-1	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} = \pm 8V			\pm 10	μ A
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V, T _J =25 $^\circ$ C			-1	μ A
		V _{DS} =-12V, V _{GS} =0V, T _J =85 $^\circ$ C			-10	
R _{DS(ON)}	Drain-source On-Resistance ^D	V _{GS} =-4.5V, I _D =-0.54A		560	680	Ω
		V _{GS} =-2.5V, I _D =-0.3A		740	900	
		V _{GS} =-1.8V, I _D =-0.2A		1000	1300	
		V _{GS} =-1.5V, I _D =-0.1A		1400	1800	
G _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-0.5A		1		S
Diode Characteristics						
V _{SD}	Diode Forward Voltage ^D	I _S =-0.2A, V _{GS} =0V			-1	V
I _S	Diode Continuous Forward Current ^A				-0.32	A
t _{rr}	Reverse Recovery Time	I _S =-0.5A, di/dt=100A/ μ s		9		ns
Q _{rr}	Reverse Recovery Charge			0.7		nC
Dynamic and Switching Parameters ^E						
Q _g	Total Gate Charge	V _{DS} =-10V, V _{GS} =-4.5V I _D =-0.5A		0.8		nC
Q _{gs}	Gate-Source Charge			0.17		
Q _{gd}	Gate-Drain Charge			0.19		
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz		55		pF
C _{oss}	Output Capacitance			5.6		
C _{rss}	Reverse Transfer Capacitance			4.6		
t _{d(on)}	Turn-On Time	V _{DD} =-10V, V _{GS} =-4.5V R _G =3 Ω , I _D =-0.5A		4.6	9	nS
t _r				6.2	12	
t _{d(off)}	Turn-Off Time			16	30	
t _f				25	48	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

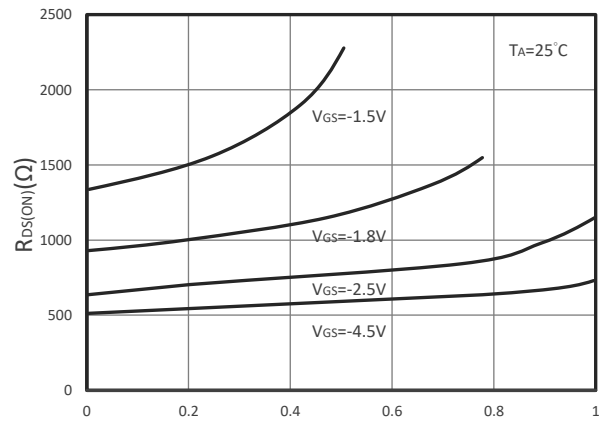
- A. Surface mounted on FR4 board using 1 in² pad size.
- B. Pulsed width limited by maximum junction temperature, T_{J(MAX)}=150 $^\circ$ C.
- C. Using \leq 10s junction-to-ambient thermal resistance is base on T_{J(MAX)}=150 $^\circ$ C.
- D. Pulse test width \leq 300 μ s and duty cycle \leq 2%.
- E. Guaranteed by design, not subject to production testing.

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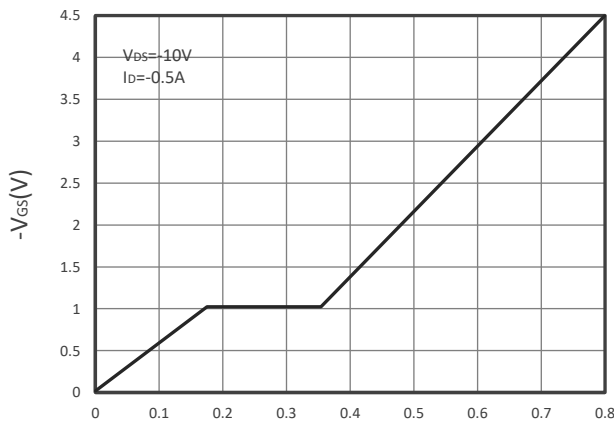
TYPICAL CHARACTERISTICS



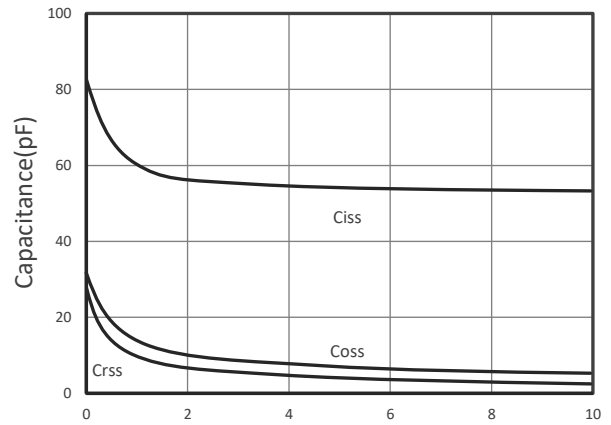
Output Characteristics



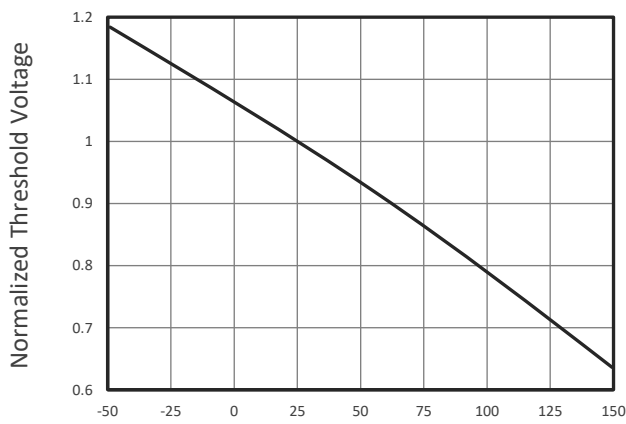
Drain-Source On Resistance



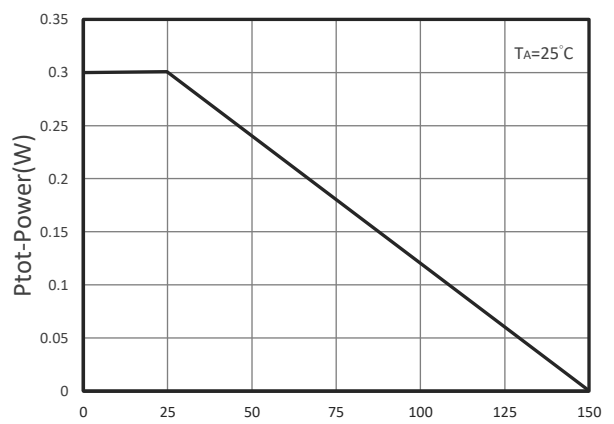
Gate Charge



Capacitance

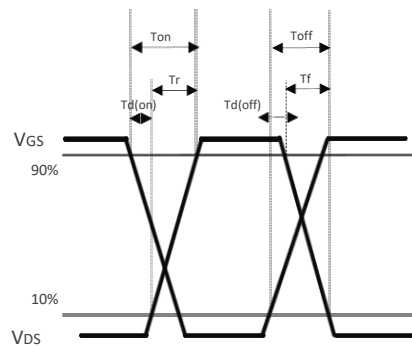
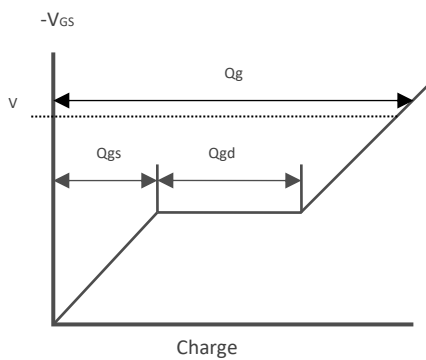
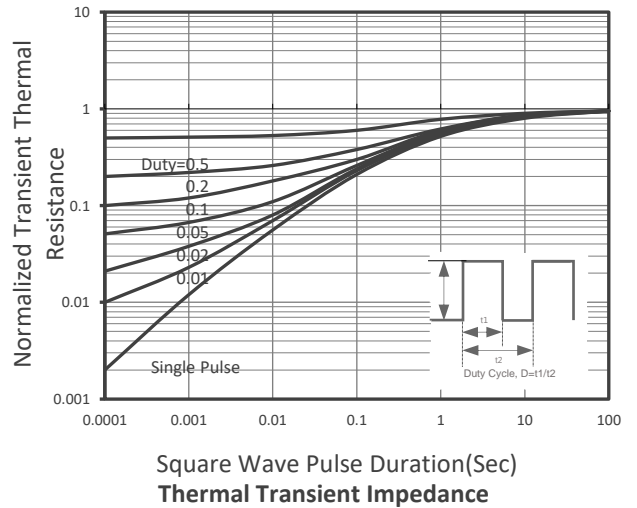
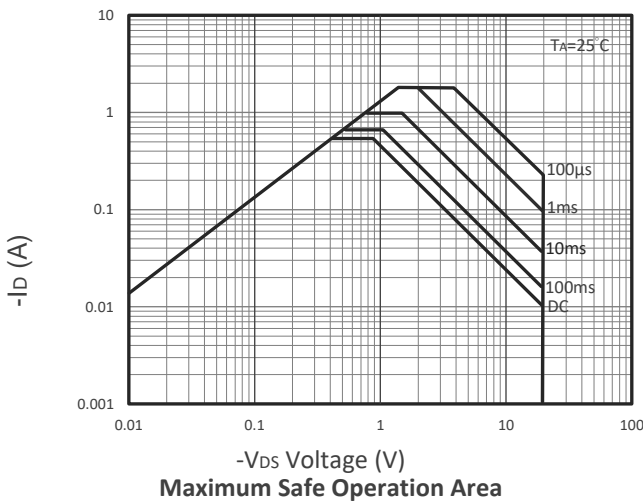
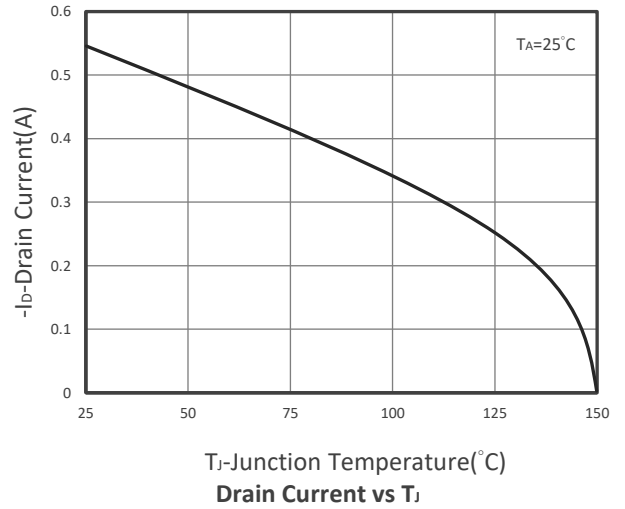
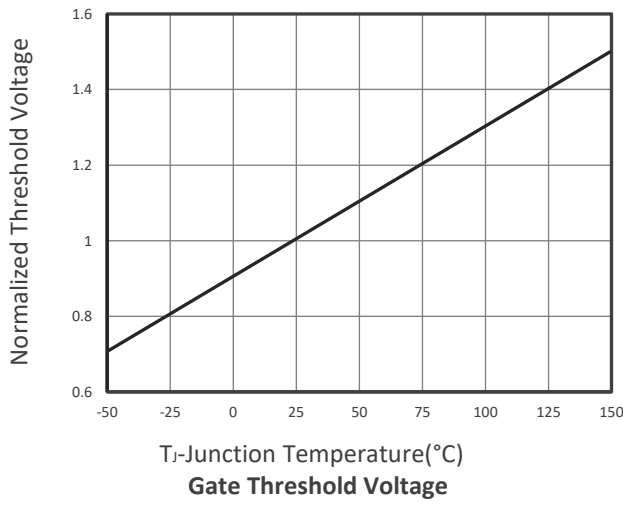


Gate Threshold Voltage



Power Dissipation

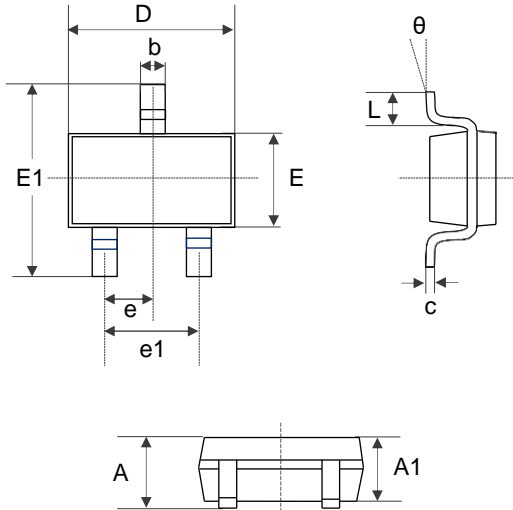
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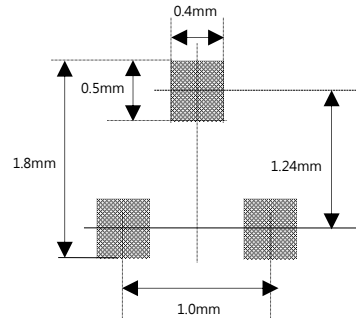
Gate Charge Waveform

Switching Time Waveform

■ SOT-523 PACKAGE DIMENSIONS



Recommended Land Pattern



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP..	
e1	0.900	1.100	0.035	0.043
L	0.100	0.30	0.004	0.012
Θ	0°	8°	0°	8°